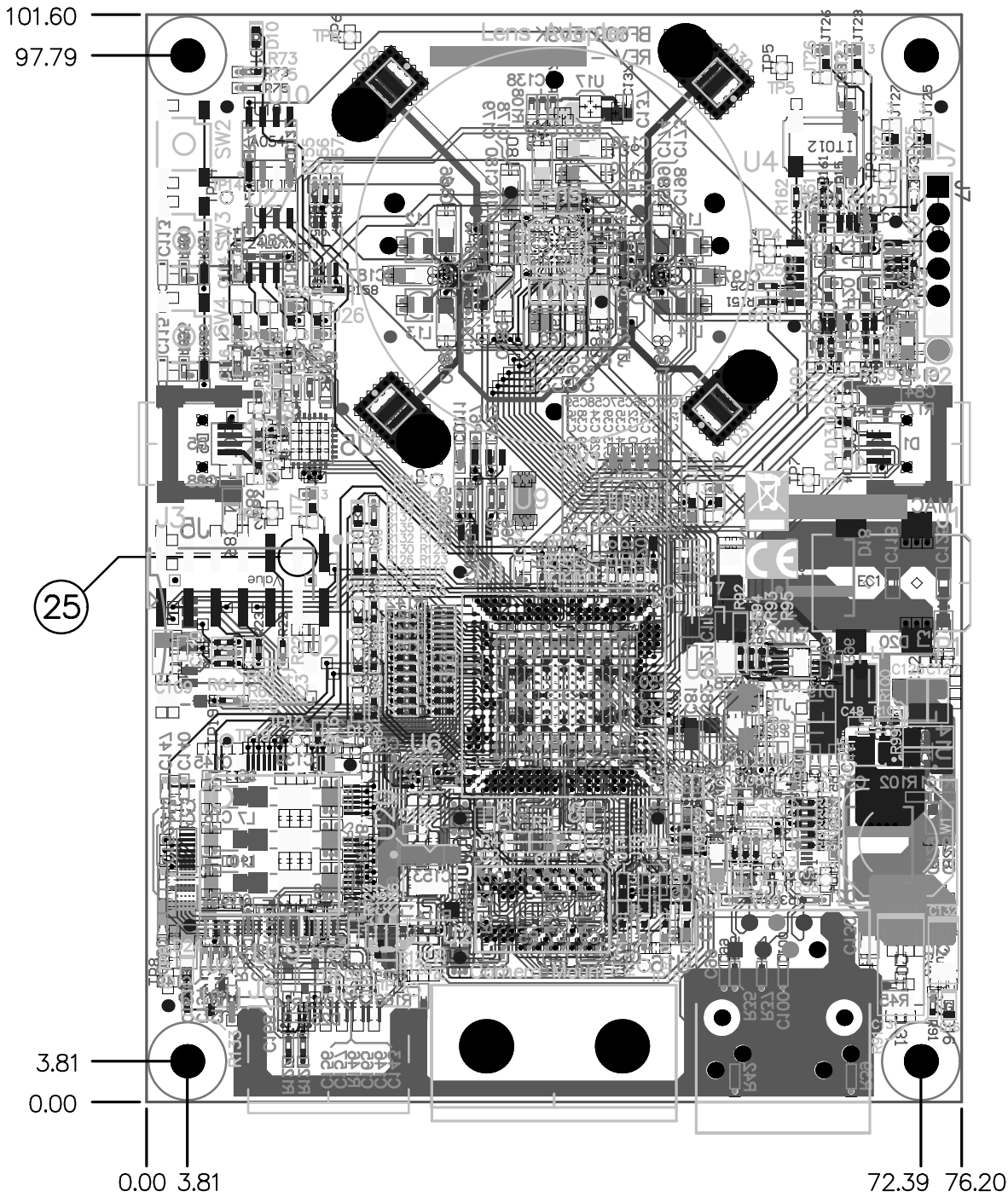


ADDITIONAL NOTES:

25. FINISHED BOARD THICKNESS = 0.063 +/- 0.007
26. CONTROLLED IMPEDANCE REQUIREMENTS: VENDOR MAY MODIFY DIELECTRIC THICKNESS BY 25% WITHOUT WRITTEN CONSENT. ANY GREATER THAN 25% REQUIRES WRITTEN CONSENT FROM AVNET ENGINEERING
- CONTROL DIFFERENTIAL IMPEDANCE TO 90-OHMS +/- 10% ON EXTERNAL LAYERS OF WIDTH 6.5 MILS
  - CONTROL DIFFERENTIAL IMPEDANCE TO 100-OHMS +/- 10% ON EXTERNAL LAYERS OF WIDTH 5.5 MILS
  - CONTROL SINGLE ENDED IMPEDANCE TO 50-OHMS +/- 10% ON ALL OTHER TRACES

SYMBOL	QUANTITY	DRILL SIZE	PLATING	TYPE
○	27	0.127mm (5mil)	PTH	Round
□	1412	0.203mm (8mil)	PTH	Round
✕	6	0.254mm (10mil)	PTH	Round
☆	3	0.4mm (15.748mil)	NPTH	Round
▽	5	0.457mm (18mil)	PTH	Round
⊕	8	0.889mm (35mil)	PTH	Round
⊗	4	0.9mm (35.433mil)	NPTH	Round
✕	4	1.016mm (40mil)	PTH	Round
B	1	1.168mm (45.984mil)	PTH	Round
A	6	1.168mm (46mil)	PTH	Round
○	4	1.3mm (51.181mil)	PTH	Round
▽	4	1.6mm (62.992mil)	NPTH	Round
◇	1	1.6mm (63mil)	NPTH	Round
D	2	1.6mm (63mil)	PTH	Round
□	2	1.676mm (66mil)	NPTH	Round
◇	1	1.803mm (71mil)	NPTH	Round
⊕	2	1.83mm (72.047mil)	NPTH	Round
E	4	3.175mm (125mil)	PTH	Round
C	4	3.175mm (125mil)	NPTH	Round
☆	2	3.251mm (128mil)	NPTH	Round
⊗	2	3.556mm (140mil)	PTH	Round
	1504 Total			



AES	CUSTOMER: AVNET ELECTRONICS MARKETING	DATE: FEB-17-13
	TITLE: BF609-EVSK DEVELOPMENT BOARD	REV: B
	LEVEL: <del>TOP LAYER</del> LAYER 6	

NOTES: UNLESS OTHERWISE SPECIFIED

- BOARD SHALL BE FABRICATED – PERFORMANCE CLASS II AS PER IPC-6011 AND IPC-6012
- VENDOR LOGO, VENDOR P/N, REVISION, AND DATE CODE OF THE MANUFACTURING SHALL BE ETCHED ON THE SOLDER SIDE. THE DATE CODE SHALL BE IN THE FORMAT: WWYY WHERE WW=WEEK AND YY=YEAR
- FABRICATE USING FILM FAB/DRILL IDENT FOR REFERENCE
- PERMANENTLY MARK BARE BOARD WITH TEST STAMP USING NON-CONDUCTIVE, RoHS COMPLIANT INK
- SILKSCREEN BOTH SIDES WITH NON-CONDUCTIVE, RoHS COMPLIANT INK, NOT ALLOWED ON COMPONENT PADS, COMPONENT MOUNTING HOLES, OR VIAS (COLOR = WHITE).
- MATERIAL: PER IPC-4101A/24/26/29/99, COPPER CLAD, HIGH TEMPERATURE FR4 CLASS EPOXY GLASS RATED UL94V-0, 0.5 OZ COPPER FOR EXTERNAL LAYERS AND 0.5 OZ COPPER FOR INTERNAL LAYERS. MUST BE RoHS COMPLIANT AND SURVIVE A LEAD-FREE ASSEMBLY MAX REFLOW OF 260 DEG C (6 PASSES)
  - Td RATING: > 340 DEG C
  - Z AXIS CTE < 3.5%
  - Tg > 170 DEG C (MIN)
- SOLDER MASK: SMOBC PER IPC-SM-840C, CLASS T, MUST BE RoHS COMPLIANT, TYP LPI, 0.0002 MIN TO 0.0008 MAX MEASURED OVER COPPER PLATING, MUST CLEAR ALL LANDS AS INDICATED ON GERBER SOLDER MASK LAYERS, (COLOR = RED)
- FINISH: ELECTRO-LESS NICKEL IMMERSION GOLD (ENIG), 2-8 MICRO INCHES GOLD OVER 150-250 MICRO INCHES NICKEL. EDGE FINGERS, WHERE PRESENT, SHALL HAVE A MINIMUM OF 30 MICRO INCHES OF HARD GOLD.
- SOLDERABILITY TEST: CATEGORY 2 OF J-STD-003
- ALL TEST POINTS SHALL BE FREE OF SOLDERMASK AND SILKSCREEN
- ALL HOLE SIZES ARE AFTER PLATING
- VENDOR MAY USE TEAR DROPS TO IMPROVE ANNULAR RINGS AS LONG AS DRC RULES ARE FOLLOWED
- FINISHED BOARDS SHALL NOT HAVE NICKS, SCRATCHES, VOIDS, EXPOSED COPPER, POOR PLATING, MISDRILLED HOLES, AND MUST BE FREE OF ANY RESIDUES
- TIE-BARS ON THERMAL PADS SHOULD BE 15 MILS MINIMUM WIDTH
- VENDOR MAY ADD COPPER THIEVING AS NEEDED TO IMPROVE MANUFACTURABILITY, THIEVING TO BE 0.030 ROUND PADS AT 0.050 SPACING. THIEVING WILL HAVE A MINIMUM OF 0.100 CLEARANCE FROM EXISTING COPPER AND SHOULD NOT BE PLACED UNDER SURFACE MOUNT DEVICES
- VENDOR SHALL REMOVE NON-FUNCTIONAL PADS
- ALL FINISHED BOARDS TO BE 100% ELECTRICALLY TESTED
- UNLESS OTHERWISE INDICATED, ALL LINEAR TOLERANCES SHALL BE XX +/- 0.010 AND XXX +/- 0.005
- VENDOR SHALL PROVIDE TDR TEST COUPON AND IMPEDANCE REPORT IF CONTROLLED IMPEDANCE TRACES PRESENT ON DESIGN (SEE 'ADDITIONAL NOTES')
- TENT ALL VIAS ON TOP SIDE WITH RoHS COMPLIANT SOLDER MASK
- NO PARTS CONTAINING LEAD MAY BE INSTALLED ON THE ASSEMBLY WITHOUT PRIOR WRITTEN CONSENT FROM AVNET ENGINEERING
- ALL SOLDERING AND CLEANING PROCESSES FOR THIS ASSEMBLY MUST BE LEAD-FREE
- MANUAL ASSEMBLY AND REWORK MUSE USE LEAD-FREE SOLDER AND FOLLOW RoHS PROCEDURES.
- THIS ASSEMBLY SHALL BE RoHS COMPLIANT. VENDOR SHALL DELIVER ASSEMBLY WITH ACCOMPANYING CERTIFICATE OF COMPLIANCE
- CONTRACT MANUFACTURER TO CLIP PIN 3 OF J2

BUILD INFO:

PAD COUNT	1982
HOLE COUNT	1504
VIA COUNT	1439
COMPONENTS	505
NET COUNT	388